## INTEGRATED CIRCUITS

## DATA SHEET

# **74LVC08A**Quad 2-input AND gate

Product specification IC24 Data Handbook

1997 Jun 30

Philips Semiconductors





**74LVC08A** 

#### **FEATURES**

- Wide supply voltage range of 1.2 V to 3.6 V
- In accordance with JEDEC standard no. 8-1A
- Inputs accept voltages up to 5.5 V
- CMOS low power consumption
- Direct interface with TTL levels

#### **DESCRIPTION**

The 74LVC08A is a high-performance, low-power, low-voltage, Si-gate CMOS device and superior to most advanced CMOS compatible TTL families.

Inputs can be driven from either 3.3 V or 5 V devices. This feature allows the use of these devices as translators in a mixed 3.3 V/5 V

The 74LVC08A provides the 2-input AND function.

#### **QUICK REFERENCE DATA**

GND = 0 V;  $T_{amb} = 25^{\circ}C$ ;  $t_{f} = t_{f} \le 2.5 \text{ ns}$ 

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t <sub>PHL</sub> /t <sub>PLH</sub>	Propagation delay nA, nB to nY	$C_L = 50 \text{ pF};$ $V_{CC} = 3.3 \text{ V}$	2.6	ns
C <sub>I</sub>	Input capacitance		5.0	pF
C <sub>PD</sub>	Power dissipation capacitance per gate	Notes 1 and 2	28	pF

#### NOTES:

C<sub>PD</sub> is used to determine the dynamic power dissipation ( $P_D$  in  $\mu W$ )

 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$  where:

 $f_i$  = input frequency in MHz;  $C_L$  = output load capacity in pF;  $f_o$  = output frequency in MHz;  $V_{CC}$  = supply voltage in V;

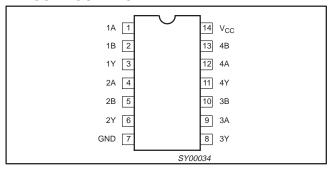
 $\sum (C_L \times V_{CC}^2 \times f_0) = \text{sum of the outputs.}$ 

2. The condition is  $V_I = GND$  to  $V_{CC}$ .

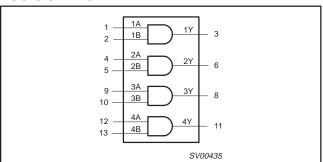
#### ORDERING INFORMATION

ONDERMINO IN ORMINATION				
PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
14-Pin Plastic SO	-40°C to +85°C	74LVC08A D	74LVC08A D	SOT108-1
14-Pin Plastic SSOP Type II	-40°C to +85°C	74LVC08A DB	74LVC08A DB	SOT337-1
14-Pin Plastic TSSOP Type I	-40°C to +85°C	74LVC08A PW	74LVC08APW DH	SOT402-1

#### **PIN CONFIGURATION**



#### **LOGIC SYMBOL**



#### PIN DESCRIPTION

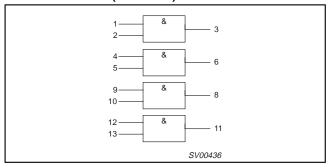
PIN NUMBER	SYMBOL	NAME AND FUNCTION
1, 4, 9, 12	1A – 4A	Data inputa
2, 5, 10, 13	1B – 4B	Data inputs
3, 6, 8, 11	1Y – 4Y	Data outputs
7	GND	Ground (0 V)
14	V <sub>CC</sub>	Positive supply voltage

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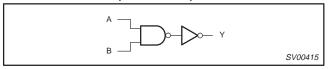
## Quad 2-input AND gate

74LVC08A

#### LOGIC SYMBOL (IEEE/IEC)



#### **LOGIC DIAGRAM (ONE GATE)**



#### **FUNCTION TABLE**

INP	OUTPUTS	
nA	nB	nY
L	L	L
L	Н	L
Н	L	L
Н	Н	Н

#### NOTES:

H = HIGH voltage level L = LOW voltage level

#### RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	LIM	UNIT	
STIMBUL	PARAMETER	CONDITIONS	MIN	MAX	UNII
V <sub>CC</sub>	DC supply voltage (for max. speed performance)		2.7	3.6	V
V <sub>CC</sub>	DC supply voltage (for low-voltage applications)		1.2	3.6	V
VI	DC input voltage range		0	5.5	V
V <sub>O</sub>	DC output voltage range; output HIGH or LOW state		0	V <sub>CC</sub>	V
T <sub>amb</sub>	Operating ambient temperature range in free-air		-40	+85	°C
t <sub>r</sub> , t <sub>f</sub>	Input rise and fall times	$V_{CC} = 1.2 \text{ to } 2.7V$ $V_{CC} = 2.7 \text{ to } 3.6V$	0	20 10	ns/V

#### ABSOLUTE MAXIMUM RATINGS<sup>1</sup>

In accordance with the Absolute Maximum Rating System (IEC 134). Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V <sub>CC</sub>	DC supply voltage		-0.5 to +6.5	V
I <sub>IK</sub>	DC input diode current	$V_1 < 0$	-50	mA
V <sub>I</sub>	DC input voltage	Note 2	-0.5 to +6.5	V
I <sub>OK</sub>	DC output diode current	$V_{O} > V_{CC}$ or $V_{O} < 0$	±50	mA
Vo	DC output voltage; output HIGH or LOW state	Note 2	$-0.5$ to $V_{CC}$ +0.5	V
ΙO	DC output source or sink current	$V_{O} = 0$ to $V_{CC}$	±50	mA
I <sub>GND</sub> , I <sub>CC</sub>	DC V <sub>CC</sub> or GND current		±100	mA
T <sub>stg</sub>	Storage temperature range		–65 to +150	°C
P <sub>TOT</sub>	Power dissipation per package  – plastic mini-pack (SO)  – plastic shrink mini-pack (SSOP and TSSOP)	above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	500 500	mW

#### NOTES:

- Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the
  device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to
  absolute-maximum-rated conditions for extended periods may affect device reliability.
- 2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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#### DC CHARACTERISTICS

Over recommended operating conditions. Voltages are referenced to GND (ground = 0V).

			L	IMITS				
SYMBOL	PARAMETER	TEST CONDITIONS	Temp = -	Temp = -40°C to +8				
			MIN	TYP <sup>1</sup>	MAX			
V	HICH level Input voltage	V <sub>CC</sub> = 1.2V	V <sub>CC</sub>			V		
V <sub>IH</sub>	HIGH level Input voltage	V <sub>CC</sub> = 2.7 to 3.6V	2.0			]		
V	LOW lovel land voltage	V <sub>CC</sub> = 1.2V			GND	\ \		
V <sub>IL</sub>	LOW level Input voltage	V <sub>CC</sub> = 2.7 to 3.6V			0.8	1 °		
		$V_{CC} = 2.7V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = -12mA$	V <sub>CC</sub> -0.5					
	HIGH level output voltage	$V_{CC} = 3.0V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = -100\mu A$	V <sub>CC</sub> -0.2	V <sub>CC</sub>		] ,		
V <sub>OH</sub>	HIGH level output voltage	$V_{CC} = 3.0V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = -18$ mA	V <sub>CC</sub> -0.6			1 °		
		$V_{CC} = 3.0V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = -24$ mA	V <sub>CC</sub> -0.8			1		
		$V_{CC} = 2.7V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = 12mA$			0.40			
V <sub>OL</sub>	LOW level output voltage	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$			0.20	V		
		$V_{CC} = 3.0V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = 24$ mA			0.55	1		
t <sub>l</sub>	Input leakage current	V <sub>CC</sub> = 3.6V; V <sub>I</sub> = 5.5V or GND		±0.1	±5	μΑ		
I <sub>CC</sub>	Quiescent supply current	$V_{CC} = 3.6V; V_I = V_{CC} \text{ or GND}; I_O = 0$		0.1	10	μΑ		
Δl <sub>CC</sub>	Additional quiescent supply current per input pin	$V_{CC} = 2.7 \text{V to } 3.6 \text{V}; V_{I} = V_{CC} - 0.6 \text{V}; I_{O} = 0$		5	500	μА		

#### NOTE:

#### **AC CHARACTERISTICS**

GND = 0 V;  $t_r = t_f \le 2.5 \text{ ns}$ ;  $C_L = 50 \text{ pF}$ 

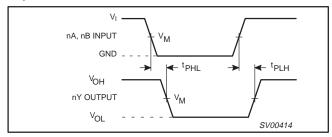
				LIMITS							
SYMBOL	PARAMETER	WAVEFORM	$V_{CC} = 3.3V \pm 0.3V$			\	/ <sub>CC</sub> = 2.7\	/	V <sub>CC</sub> = 1.2V	UNIT	
			MIN	MIN TYP <sup>1</sup> MAX MIN TYP MA		MAX	TYP				
t <sub>PHL</sub> /	Propagation delay nA, nB to nY	1, 2	1.5	2.6	5.1	1.5	3.0	6.1	16	ns	

#### NOTE:

#### **AC WAVEFORMS**

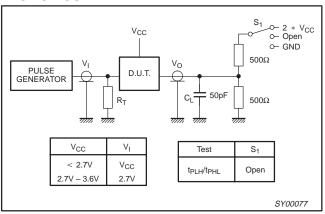
 $V_M$  = 1.5 V at  $V_{CC} \ge 2.7$  V  $V_M$  = 0.5 •  $V_{CC}$  at  $V_{CC} < 2.7$  V

 $V_{\mbox{\scriptsize OL}}$  and  $V_{\mbox{\scriptsize OH}}$  are the typical output voltage drop that occur with the output load.



Waveform 1. Input (nA, nB) to output (nY) propagation delays.

#### **TEST CIRCUIT**



Waveform 2. Load circuitry for switching times.

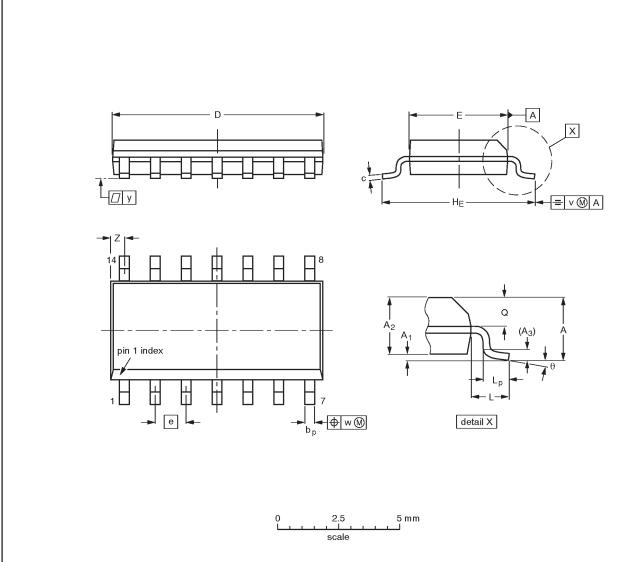
<sup>1.</sup> All typical values are at  $V_{CC}$  = 3.3V and  $T_{amb}$  = 25°C.

<sup>1.</sup> These typical values are at  $V_{CC}$  = 3.3V and  $T_{amb}$  = 25°C.

Product specification

#### SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	Α1	A <sub>2</sub>	A <sub>3</sub>	bp	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	1 // //60	0.0098 0.0039		0.01		0.0098 0.0075	0.35 0.34	0.16 0.15	0.050	0.24 0.23	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	0°

#### Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

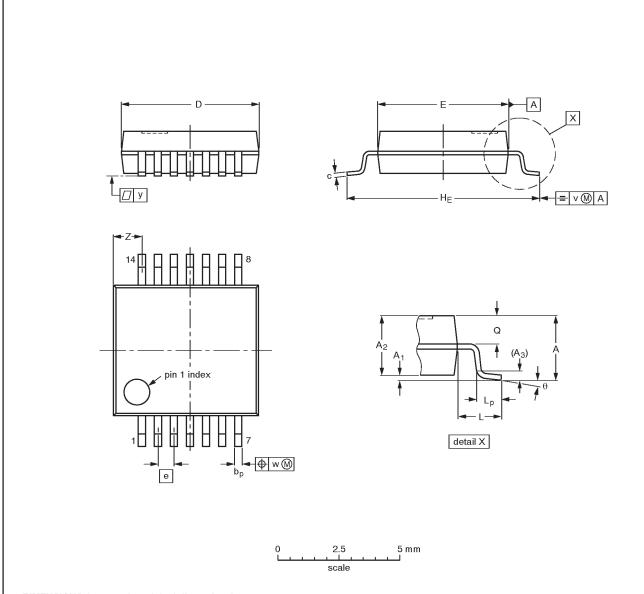
OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT108-1	076E06\$	MS-012AB			<del>91-08-13</del> 95-01-23

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#### SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1



#### DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	<b>A</b> <sub>3</sub>	bp	c	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Ø	٧	w	у	Z <sup>(1)</sup>	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

#### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

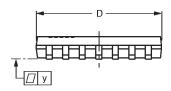
OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ	PROJECTION	1330E DATE	
SOT337-1		MO-150AB			<del>95-02-04</del> 96-01-18	

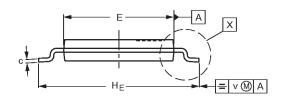
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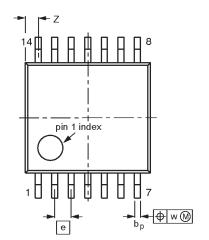
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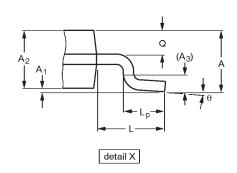
TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

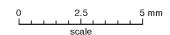
SOT402-1











#### DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A <sub>2</sub>	A <sub>3</sub>	bр	c	D <sup>(1)</sup>	E <sup>(2)</sup>	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

#### Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT402-1		MO-153				<del>-94-07-12</del> 95-04-04	

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DEFINITIONS						
Data Sheet Identification	Product Status	Definition				
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.				
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philip Semiconductors reserves the right to make changes at any time without notice in order to improve desig and supply the best possible product.				
Product Specification	Full Production	This data sheet contains Final Specifications. Philips Semiconductors reserves the right to make changes at any time without notice, in order to improve design and supply the best possible product.				

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